

Amendments to the Abstract

Please **add** the following Abstract to this application.

-- An integrated circuit die for a flip chip has circular die bond pads. Circular die bond pads allows for a higher density of bond pads when a mating printed circuit board has routing lines between its corresponding pads. In one form, there is provided a flip chip having a die and a plurality of die bond pads situated on the die. Each die bond pad of the die is circular.--